



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

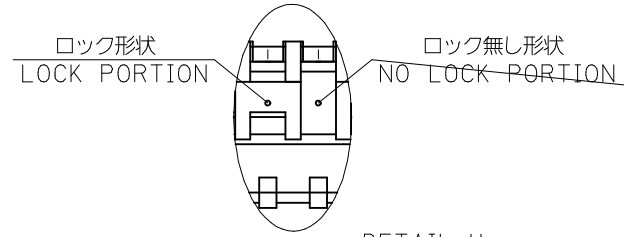
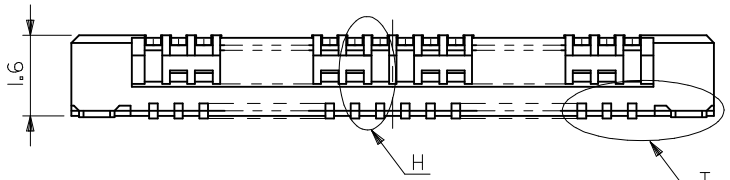
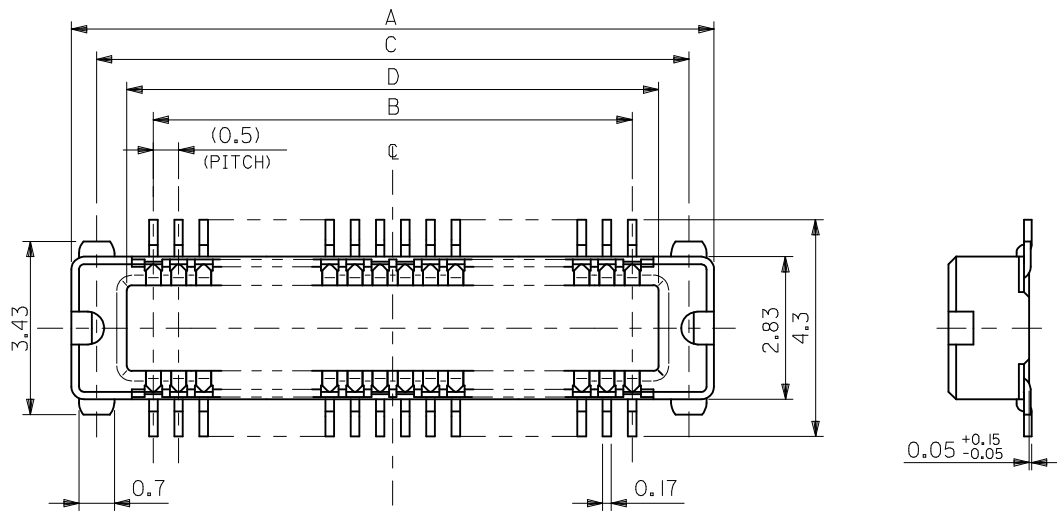
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



注記
NOTES:

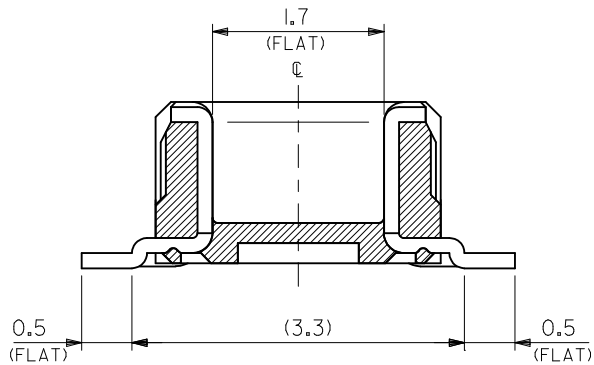
1. 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.2)
NAIL: COPPER ALLOY (t=0.2)
2. メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上。
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM.
半田付け部: 金メッキ 0.4マイクロメートル以下。
SOLDER TAIL AREA: GOLD 0.4 MICROMETER MAXIMUM.
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上。
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM.
ネイル
NAIL
錫メッキ 3.0マイクロメートル以上
Sn 3.0 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上。
UNDER PLATING: Ni 1.0 MICROMETER MINIMUM.
3. テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
4. 嵌合相手: 54363-****
MATED CONN.: 54363-****
5. この製品は55201-**01, (エンボス梱包品 55201-**08) の鉛フリー品です。
THIS PRODUCT IS 'LEAD FREE' OF 55201-**01, (EMBOSSED TAPE PKG 55201-**08)



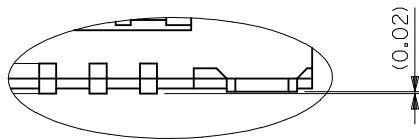
DETAIL H
SCALE 20

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—#	30.55	31.75	29.5	32.75	55201-1278	55201-1271	120
—#	20.55	21.75	19.5	22.75	55201-0878	55201-0871	80
12	13.05	14.25	12	15.25	55201-0578	55201-0571	50
20	10.55	11.75	9.5	12.75	55201-0478	55201-0471	40
30	8.05	9.25	7	10.25	55201-0378	55201-0371	30
20	5.55	6.75	4.5	7.75	55201-0278	55201-0271	20
□ツク数 LOCKS	D	C	B	A	エンボス梱包品 EMBOSSED TAPE PACKAGING	製品番号 MATERIAL NO.	極数 CIRCUITS

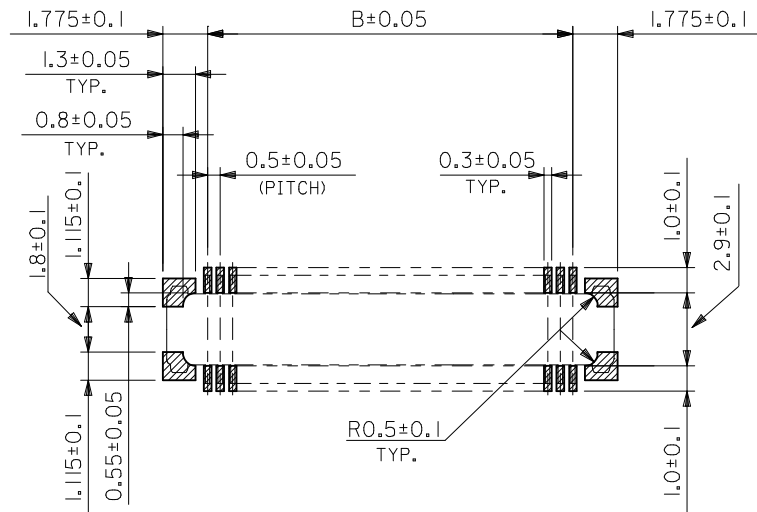
REVISED EC NO: J2009-0259 DRWN: YOSHIDAM 2008/08/07 CHKD: THARUYAMA 2008/08/07 APPR: NUKITA 2008/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY A. IDA	DATE '04/01/06	TITLE 0.5 B/B PLUG ASSY(H=2MM) WITH FITTING NAIL -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY H. TAKASE	DATE '04/01/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY J. MIYAZAWA	DATE '04/01/06	DOCUMENT NO. SD-55201-013	SHEET NO. 1 OF 2	
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE			
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



↑部陸詳細
DETAIL T

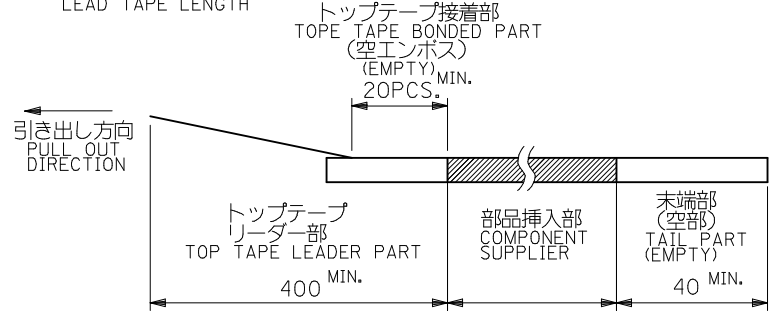
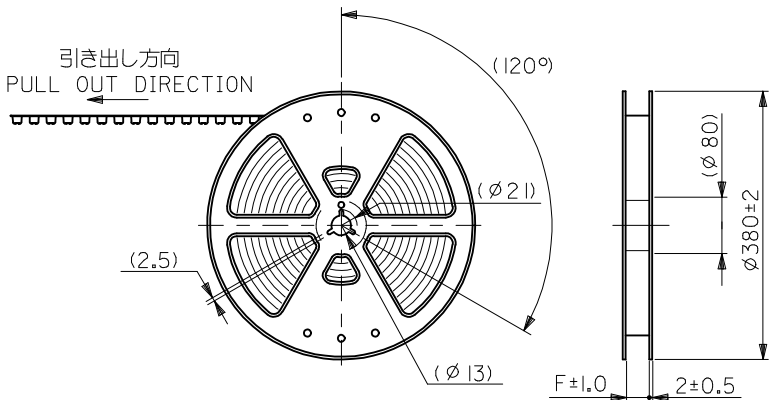


推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:5-1)

REVISED EC NO: J2009-0259 DRWN: YOSHIDAM 2008/08/07 CHKD: THARUYAMA 2008/08/07 APPR: NUKITA 2008/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY A. IDA	DATE '04/01/06	TITLE 0.5 B/B PLUG ASSY(H=2MM) WITH FITTING NAIL -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY H. TAKASE	DATE '04/01/06	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY J. MIYAZAWA	DATE '04/01/06	DOCUMENT NO. SD-55201-013	SHEET NO. 2 OF 2
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

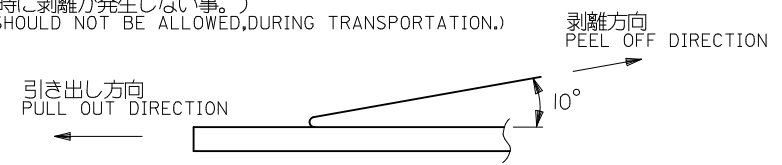
注)
NOTES

1. 製品番号 55201-**71 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55201-**71 DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：2500個/リール
NUMBER OF CONNECTORS:2500 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



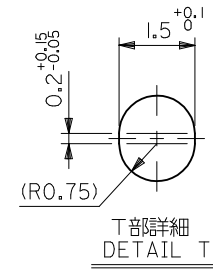
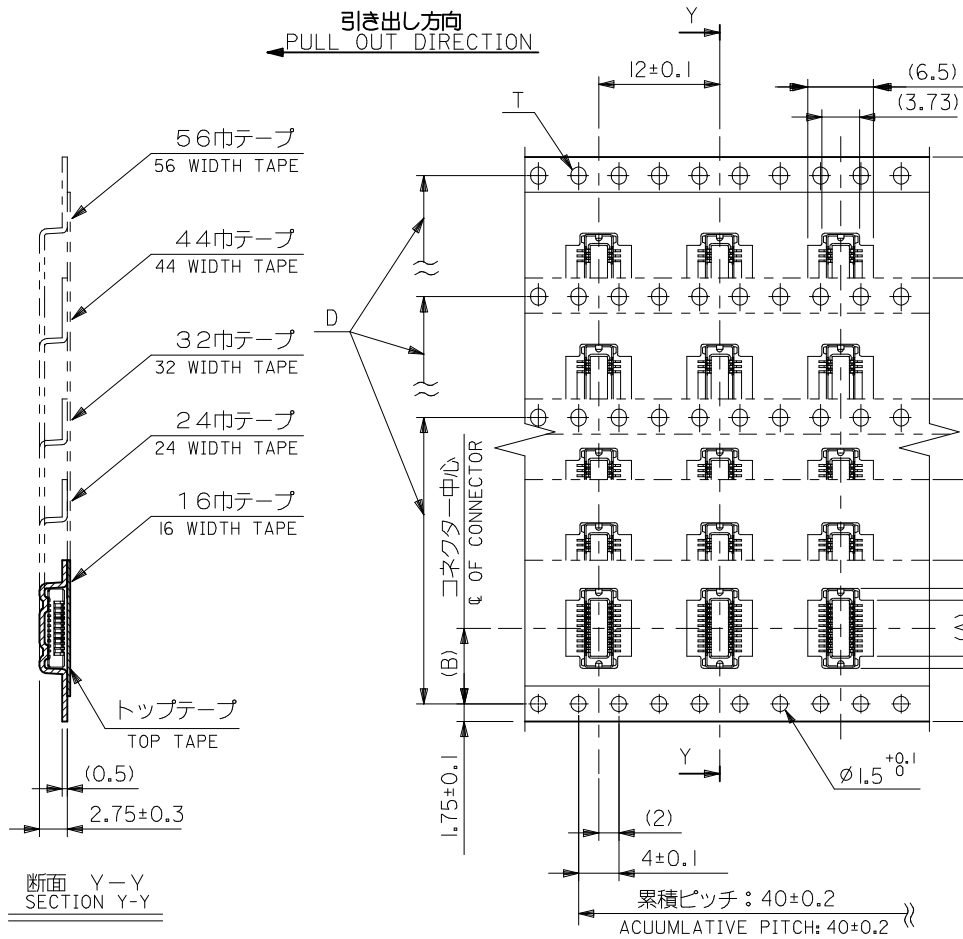
4. トップテープの剥離強度：(剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)
0. 1~1. 3N (10~130gf)

尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED,DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ：ポリプロピレン (PP)
CARRIER TAPE:POLYPROPYLENE(PP)
トップテープ：PET, PE, PEF
TOP TAPE:PET,PE,PEF
リール：ポリスチレン
REEL : POLYSTYRENE
6. この製品は55201-**01, <エンボス梱包品 55201-**08) の鉛フリー品です。
THIS PRODUCTE IS 'LEAD FREE' OF 55201-**01, (EMBOSSD TAPE PKG 55201-**08)

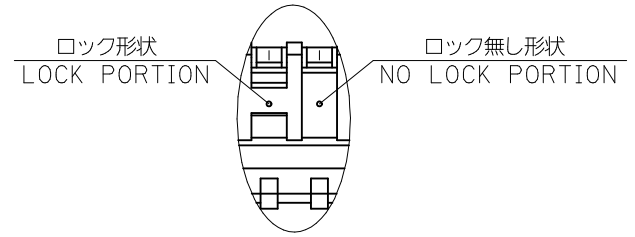
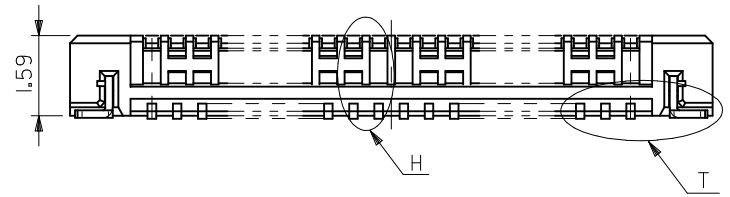
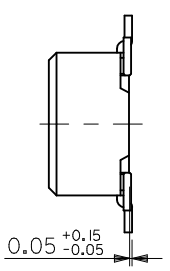
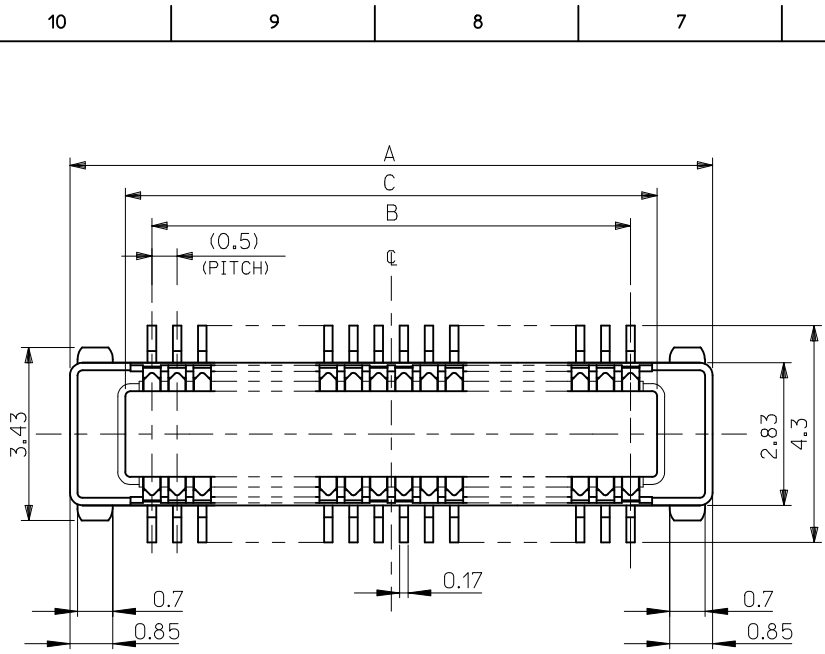
REVISED EC NO: J2009-0259 DRWN:YOSHIDAM 2008/08/07 CHKD:THARUYAMA 2008/08/07 APPR:NUKITA 2008/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY A. IDA	DATE '04/01/06	TITLE 55201-**71 TAPING PACKAGE -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY H. TAKASE	DATE '04/01/06	MOLEX INCORPORATED			
	30 OVER	±0.3	APPROVED BY J. MIYAZAWA	DATE '04/01/06	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-55201-014	SHEET NO. 1 OF 2	
REV	ANGULAR ±3 °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



断面 Y-Y
SECTION Y-Y

57.5	56±0.3	52.4	32.95	26.2	30.55	55201-1278	120	
45.5	44±0.3	40.4	22.95	20.2	20.55	55201-0878	80	
25.5	24±0.3	—	15.45	11.5	13.05	55201-0578	50	
			12.95		10.55	55201-0478	40	
			10.45		8.05	55201-0378	30	
17.5	16±0.3	—	7.95	7.5	5.55	55201-0278	20	
F	E キャリアテープ幅 CARRIER TAPE WIDTH		D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2009-0259 DRWN: YOSHIDAM 2008/08/07 CHKD: THARUYAMA 2008/08/07 APPR: NUKITA 2008/12/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY A. IDA	DATE '04/01/06	TITLE 55201-**71 TAPING PACKAGE -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY H. TAKASE	DATE '04/01/06	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY J. MIYAZAWA	DATE '04/01/06	DOCUMENT NO. SD-55201-014	SHEET NO. 2 OF 2		
REV	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



DETAIL H
SCALE 20-1

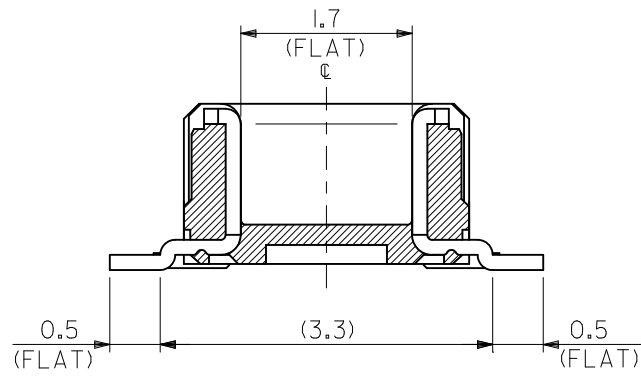
注記

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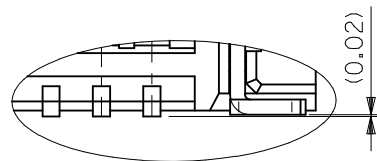
- 材質
MATERIAL
ハウジング: LCP、ガラス充填、黒色, UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER, GLASS FILLED, BLACK, UL94V-0
ターミナル: 黄銅 (t=0.15)
TERMINAL: BRASS (t=0.15)
ネイル: リン青銅 (t=0.15)
NAIL: PHOSPHOR BRONZE (t=0.15)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25 μm以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM.
半田付け部: 金メッキ 0.1 μm以上
SOLDER TAIL: GOLD 0.1 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.5 μm以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM.
ネイル
NAIL
鍍メッキ: 1.0 μm以上
TIN PLATING: 1.0 MICROMETER MINIMUM.
下地メッキ: ニッケルメッキ 1.0 μm以上
UNDER PLATING: NICKEL PLATING 1.0 MICROMETER MINIMUM.
- テール平坦度は、0.08以下。テールとネイルを併せた平坦度は、0.1以下とする。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 54363-****
MATED CONN.: 54363-****
- 本製品は55201-**78 ネイル圧入品です。
THIS PRODUCT IS NAIL-FITTING ITEM OF 55201-**78.

20.55	19.5	22.75	55201-0878	80
C	B	A	EMBOSSED PACKAGE	Ck+
			ORDER No.	オーダー番号
CONNECTOR SERIES No. 55201-**71				

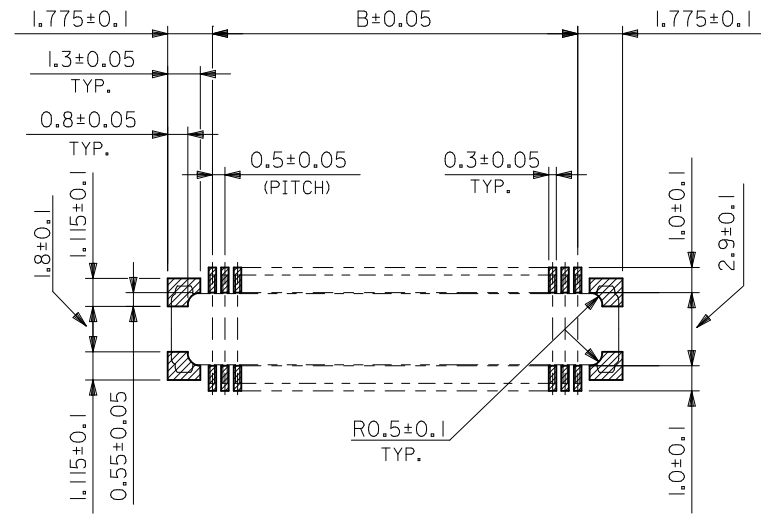
REVISED EC NO: J2011-0841 DRWNG: KTOYODA CHKD: APPR: MSASAO	DESCRIPTION 2010/12/16 2011/02/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY KTOYODA	DATE 2010/12/16	TITLE 0.5 B/B PLUG ASSY WITH FITTING NAIL				
		10 OVER 30 UNDER	±0.25	CHECKED BY		DATE				
		30 OVER	±0.3	APPROVED BY MSASAO		DATE 2011/02/15		MOLEX INCORPORATED		
		ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



製品断面図 (半田付け部、吸着面寸法)
DETAIL FOR SOLDERING AND VACUUM AREA



DETAIL T
T部詳細



推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:5-1)

REVISED EC NO: J2011-0841 DRWNG: KTOYODA 2010/12/16 CHKD: APPR: MSASAO 2011/02/15 REV: 0	DESCRIPTION 2011/02/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	1:1	METRIC		
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
		10 OVER 30 UNDER	±0.25	KTOYODA	2010/12/16	0.5 B/B PLUG ASSY WITH FITTING NAIL		
		30 OVER	±0.3	CHECKED BY	DATE			
ANGULAR ±1 °		APPROVED BY	DATE	MOLEX INCORPORATED				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MSASAO	2011/02/15	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
		SEE TABLE		SD-55201-015		2 OF 2		
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
		A3						